



SURFACE MOUNT ZENER DIODE

Features

- Flat Lead Package Design for Low Profile and High Power Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Alloy Leadframe. Solderable per MIL-STD-202, Method 208 ©3)
- Polarity: Cathode Band
- Weight: 0.015 grams (Approximate)

SOD123F (Type B)





Top View

Bottom View

Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging
BZT52HC18WFQ-7	Automotive	SOD123F (Type B)	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



XX = Product Type Marking Code (See Electrical Characteristics Table)

YM = Date Code Marking Y = Year (ex: G = 2019)

M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	202	1 2	2022		2025	202	6 2	2027	2028
Code	F	G	Н	I		J		М	N		0	Р
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Forward Voltage (Note 6)	@ I _F = 10mA	V _F	0.9	V
Forward Current		l _F	250	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	P _D	375	mW
Power Dissipation (Note 8)	P _D	830	mW
Thermal Resistance, Junction to Ambient Air (Note 7)	$R_{ heta JA}$	330	°C/W
Thermal Resistance, Junction to Ambient Air (Note 8)	$R_{ heta JA}$	150	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Notes:

- 6. Short duration pulse test used to minimize self-heating effect.
 7. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com/package-outlines.html.
 8. Device mounted on FR-4 PCB with mounting pad for cathode 1cm².



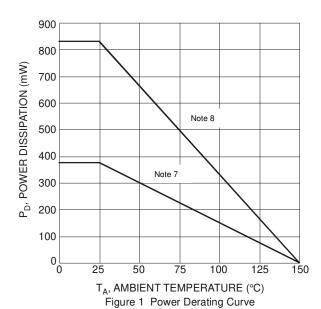
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

		Zener Voltage Range (Note 9)		Maximum Zener Impedance (Note 10)			Temperature Coefficient		Total Capacitance	Maximum Reverse Current (Note 9)		
Type Number	Marking Codes	V _z @	Vz @ IzT IzT		Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	T _C @ I _{ZT}		C_T @ f = 1MHz, $V_R = 0V$	I _R	@ V _R
		Min (V)	Max (V)	mA	2	2	mA	Min (mV/°C)	Max (mV/°C)	Max (pF)	μΑ	٧
BZT52HC18WFQ	WL	16.8	19.1	5	20	170	1	12.4	16.0	70	0.05	12.6

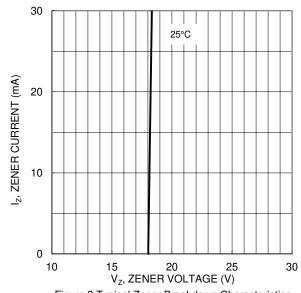
1000

Notes:

9. Short duration pulse test used to minimize self-heating effect.



I_F, INSTANTANEOUS FORWARD CURRENT (mA) 100 10 0.1 0.01 0.001 300 400 500 600 700 800 900 1000 V_E, INSTANTANEOUS FORWARD VOLTAGE (mV) Figure 2 Typical Forward Characteristics

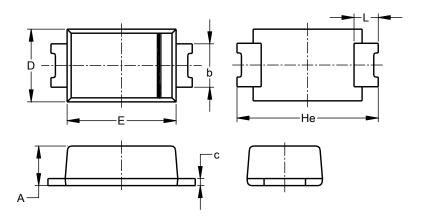




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOD123F (Type B)

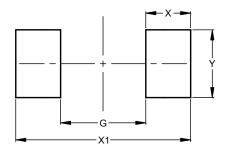


SOD123F (Type B)							
Dim	Min	Max	Тур				
Α	0.81	1.15					
b	0.80	1.35					
С	0.05	0.30					
D	1.70	1.90	1.80				
Е	2.60	2.80	2.70				
He	3.30	3.70	3.50				
L	0.35	0.85					
All	Dimen	sions	in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOD123F (Type B)



Dimensions	Value (in mm)
G	1.90
Х	1.00
X1	3.90
γ	1.50



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